

**DESCRIPTION**

The AM2312A is available in SOT-23S Package.

$B_{VDSS}$	$R_{DS(ON)}$	$I_D$
20V	15m $\Omega$	7A

**APPLICATION**

- Hand-Held Instruments
- Load Switch

**ORDERING INFORMATION**

Package Type	Part Number	
SOT-23S SPQ: 3,000pcs/Reel	E3S	AM2312AE3SVR
Note	V: Halogen free Package R: Tape & Reel	
AiT provides all RoHS products		

**ABSOLUTE MAXIMUM RATINGS**

$T_C=25^\circ\text{C}$  Unless otherwise noted

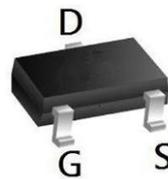
$V_{DS}$ , Drain-Source Voltage	20V	
$V_{GS}$ , Gate-Source Voltage	$\pm 12\text{V}$	
$I_D^{(1)}$ , Drain Current- Continuous	$T_A=25^\circ\text{C}$	7A
	$T_A=70^\circ\text{C}$	5A
$I_{DM}^{(2)}$ , Drain Current Pulsed	17A	
$P_D^{(3)}$ , Total Power Dissipation	$T_A=25^\circ\text{C}$	1W
	$T_A=70^\circ\text{C}$	0.66W
$T_J$ , Operating Junction Temperature Range	$-55^\circ\text{C}\sim+150^\circ\text{C}$	
$T_{STG}$ , Storage Temperature Range	$-55^\circ\text{C}\sim+150^\circ\text{C}$	
$R_{\theta JA}^{(1)}$ , Thermal Resistance Junction-Ambient	120 $^\circ\text{C}/\text{W}$	

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

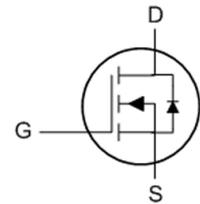
- (1) Surface Mounted on FR4 Board,  $t \leq 10$  sec.
- (2) The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- (3) The power dissipation is limited by  $150^\circ\text{C}$  junction temperature

**FEATURE**

- $V_{DS} = 20\text{V}$ ,  $I_D = 7\text{A}$
- Green Device Available (RoHS Compliant)
- Super Low Gate Charge
- Excellent dv/dt Immunity
- Advanced High Cell Density Trench Technology
- SOT-23S Package.

**PIN DESCRIPTION**

SOT-23S



Pin#	Symbol	Function
1	G	Gate
2	S	Source
3	D	Drain



**ELECTRICAL CHARACTERISTICS**

T<sub>J</sub>=25°C, unless otherwise specified.

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> = 250μA	20	-	-	V
BVDSS Temperature Coefficient	ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	Reference to 25°C, I <sub>D</sub> =1mA	-	0.018	-	V/°C
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =16V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	-	-	1	μA
		V <sub>DS</sub> =16V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	-	-	5	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V, V <sub>DS</sub> = 0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS (th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = 250μA	0.35	-	1	V
V <sub>GS (th)</sub> Temperature Coefficient	ΔV <sub>GS (th)</sub>		-	-3.1	-	mV/°C
Drain-Source On-Static Resistance <sup>(2)</sup>	R <sub>DS (on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 4A	-	15	20	mΩ
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 3A	-	20	25	
		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 2A	-	40	50	
Forward Transconductance	G <sub>fs</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 4A	-	30	-	S
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 15V, V <sub>GS</sub> =0V, f=1MHz	-	670	-	pF
Output Capacitance	C <sub>oss</sub>		-	75	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	68	-	
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 4A, R <sub>G</sub> =3.3Ω, V <sub>GS</sub> = 4.5V	-	5.2	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	34	-	
Turn-off Delay Time	t <sub>d(off)</sub>		-	23	-	
Turn-off Fall Time	t <sub>f</sub>		-	9.2	-	
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 4.5V I <sub>D</sub> = 4A	-	8.6	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	1.37	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	2.3	-	
<b>Diode Characteristics</b>						
Drain Forward Current <sup>(1)(3)</sup>	I <sub>S</sub>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	-	-	6	A
Pulsed Source Current <sup>(2)(3)</sup>	I <sub>SM</sub>		-	-	17	A
Diode Forward Voltage <sup>(2)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	-	-	1.2	V

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.

2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%

3. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



## TYPICAL PERFORMANCE CHARACTERISTICS

Fig 1. Typical Output Characteristics

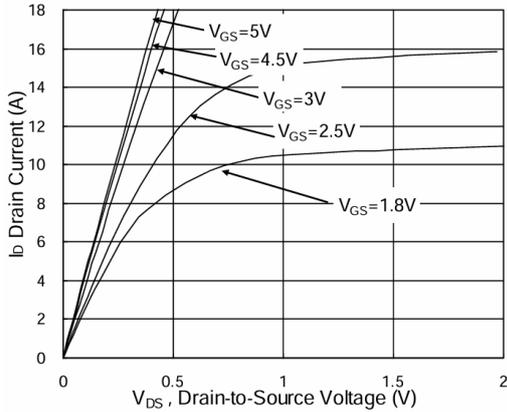


Fig 2. On-Resistance vs. Gate-Source

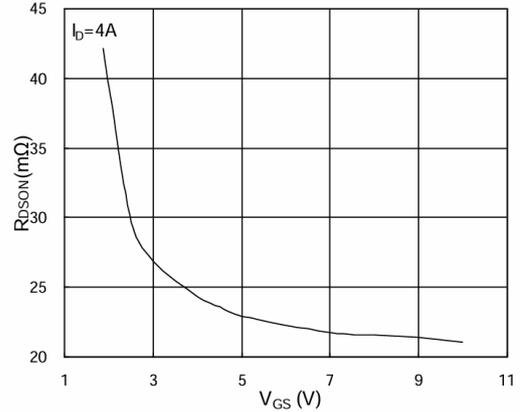


Fig 3. Forward Characteristics of Reverse

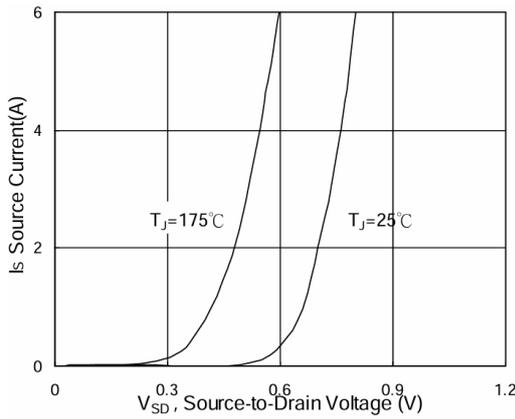


Fig 4. Gate-Charge Characteristics

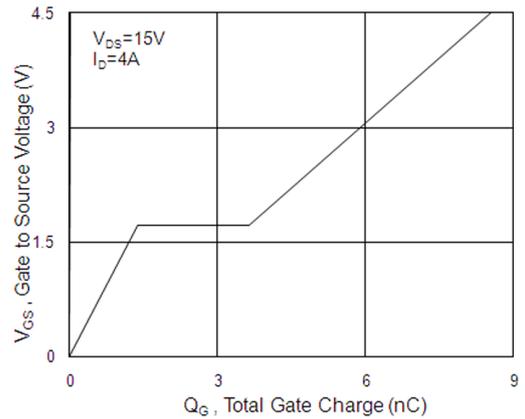


Fig 5. Normalized  $V_{GS(th)}$  vs.  $T_J$

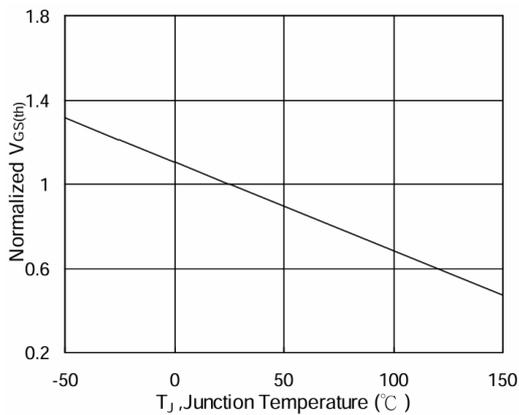


Fig 6. Normalized  $R_{DS(on)}$  vs.  $T_J$

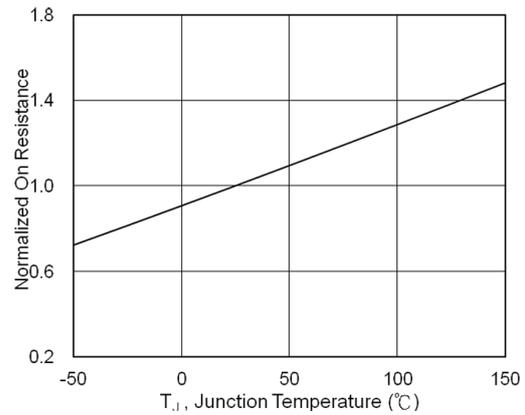




Fig 7. Capacitance

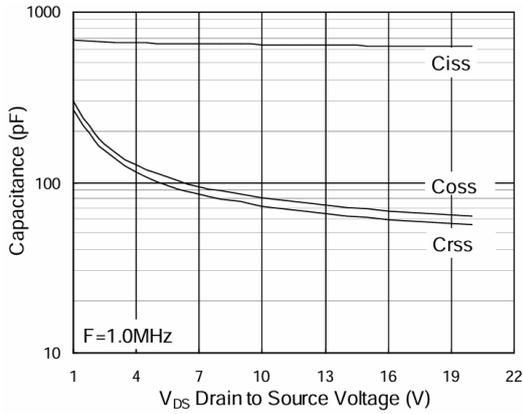


Fig 8. Safe Operating Area

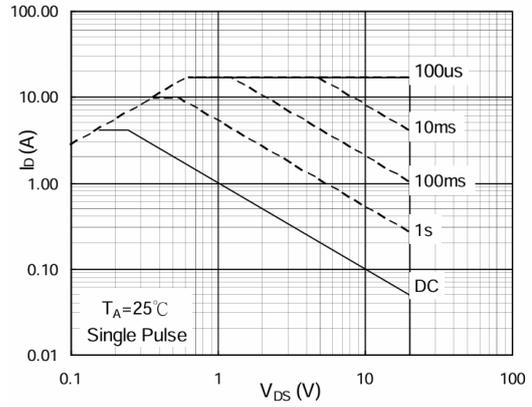


Fig 9. Normalized Maximum Transient Thermal Impedance

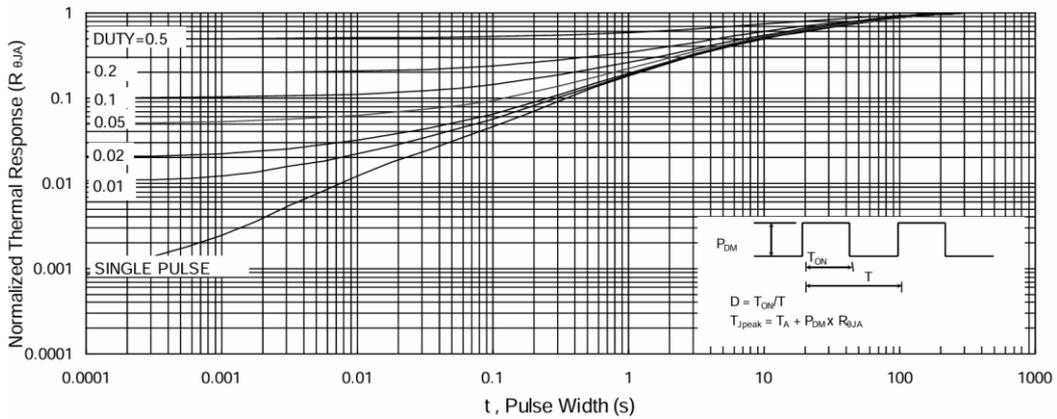


Fig 10. Switching Time Waveform

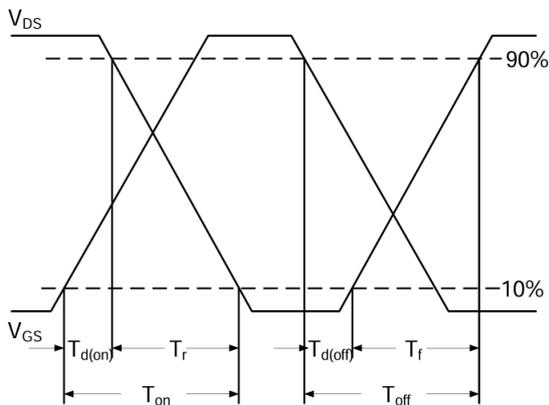
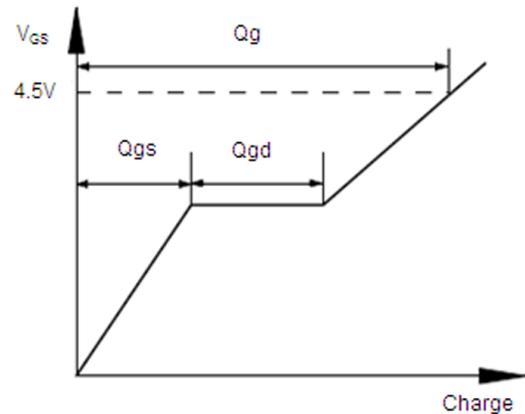


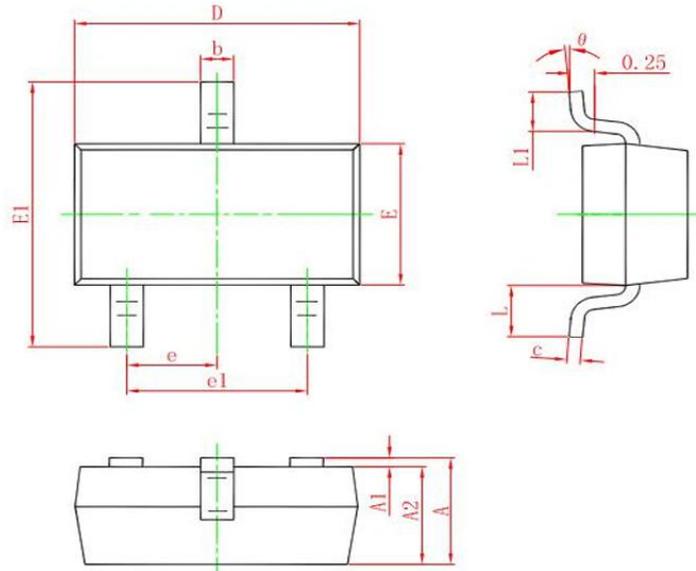
Fig 11. Gate Charge Waveform





**PACKAGE INFORMATION**

Dimension in SOT-23S (Unit: mm)



Symbol	Millimeters (mm)	
	Min.	Max.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950 TYP.	
e1	1.800	2.000
L	0.550 REF.	
L1	0.300	0.500
θ	0°	8°



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